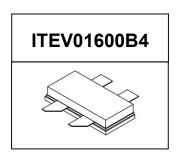
600W, 50V High Power RF LDMOS FETs

Description

The ITEV01600B4 is a 600-watt capable, high performance, unmatched LDMOS FET, designed for HF/VHF. It can be used for both CW and pulse application.

It is featured for high power and high ruggedness, low cost, suitable for ISM RF Energy application.



• Typical Performance (On Innogration 13.56MHz fixture with device soldered):

ITEV01600B4 VGS=3.36V VDS=50V IDQ=200mA CW							
Freq(MHz)	Pout(dBm)	Pout(W)	IDS(A)	Pin(dBm)	Gain(dB)	Eff(%)	
13.56	58.02	633.9	16.38	42.37	15.65	77.40	
13.56	57.8	602.6	15.97	41.38	16.42	75.46	
13.56	57.59	574.1	15.6	40.47	17.12	73.60	
13.56	57.36	544.5	15.25	39.47	17.89	71.41	
13.56	57.1	512.9	14.83	38.46	18.64	69.17	
13.56	56.82	480.8	14.43	37.49	19.33	66.64	
13.56	56.5	446.7	14	36.49	20.01	63.81	
13.56	56.14	411.1	13.49	35.51	20.63	60.96	

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- On chip RC network enable high stability and ruggedness
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Excellent thermal stability, low HCI drift
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	135	Vdc
GateSource Voltage	V _{GS}	-7 to +10	Vdc
Operating Voltage	V_{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	T₃	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case ,Case Temperature	Do 10	0.4	°C/W
80°C, 600W CW, 50 Vdc, IDQ = 200 mA	Rejc	0.4	-C/VV
Transient thermal impedance from junction to case	7th	0.08	0000
Tj = 150° C; tp = 100 us; Duty cycle = 20 %	Zth	0.08	°C/W

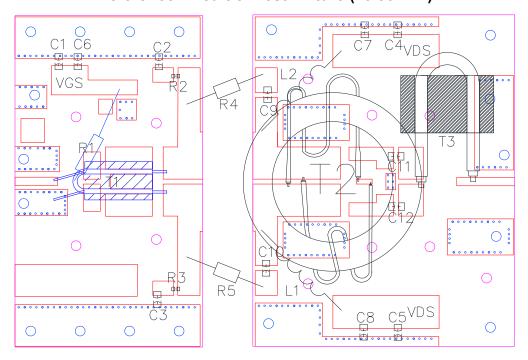
Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics (Per Side)					
Drain-Source Voltage	V	130			V
V _{GS} =0, I _{DS} =18.0mA	V _{(BR)DSS}	130			V
Zero Gate Voltage Drain Leakage Current				1	
$(V_{DS} = 50V, V_{GS} = 0 V)$	I _{DSS}			Į.	μΑ
Gate—Source Leakage Current				4	^
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}			1	μΑ
Gate Threshold Voltage	V (4b)		2.6		V
$(V_{DS} = 50V, I_D = 600 \mu A)$	V _{GS} (th)	V _{GS} (III)			V
Gate Quiescent Voltage	V		3.36		V
(V_{DD} = 50 V, I_{D} = 200 mA, Measured in Functional Test)	$V_{GS(Q)}$		3.30		V
Common Source Input Capacitance	C _{ISS}		200		pF
(V $_{GS}$ = 0V, V $_{DS}$ =50 V, f = 1 MHz) Each section side of device					
measured					
Common Source Output Capacitance	Coss		50		pF
(V_{GS} = 0V, V_{DS} =50 V, f = 1 MHz) Each section side of device					
measured					
Common Source Feedback Capacitance	C _{RSS}		1		pF
(V $_{\rm GS}$ = 0V, V $_{\rm DS}$ =50 V, f = 1 MHz) Each section side of device					
measured					

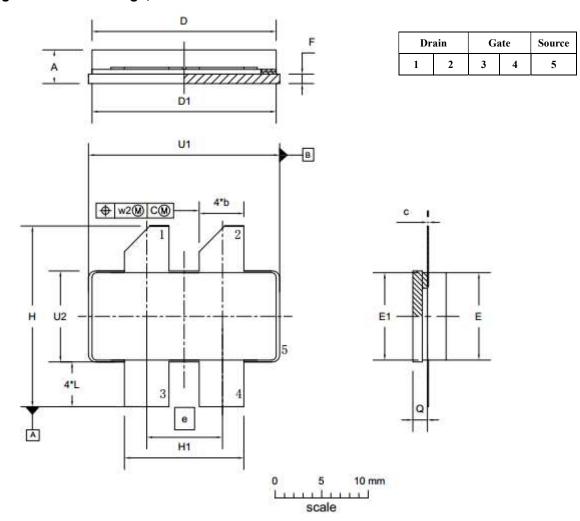
Reference Circuit of Test Fixture (13.56MHz)



Component	Description	Suggestion
C1~C5	10uF Ceramic multilayer capacitor	
C6~C12	Ceramic multilayer capacitor, 10nF	
R1	300 Ω	
R2,R3	10 Ω	
R4,R5	200 Ω Power resistor	
L1,L2	No.43 ferrite core ,10 turns	
T1	4:1 No.43 ferrite core	
T2	4:1 No.43 ferrite core,12.5ohm coaxial cable	SFF-12.5-1.5
	300mm	
Т3	25ohm No.43 ferrite core, 150mm	SFF-25-1.5
PCB	0.762mm [0.030"] thick, εr=3.48, Rogers RO43	50B, 1 oz. copper

Package Outline

Earless Flanged Ceramic Package; 4 leads



UNIT	A	b	С	D	D ₁	е	E	E ₁	F	Н	H1	L	Q	U ₁	U ₂	W ₁	W ₂
	4.72	4.67	0.15	20.02	19.96	7.00	9.50	9.53	1.14	19.94	12.98	5.33	1.70	20.70	9.91	0.25	0.51
mm	3.43	4.93	0.08	19.61	19.66	7.90	9.30	9.25	0.89	18.92	12.73	4.32	1.45	20.45	9.65	0.25	0.51
inches	0.186	0.194	0.006	0.788	0.786	0.044	0.374	0.375	0.045	0.785	0.511	0.210	0.067	0.815	0.390	0.04	0.00
inches	0.135	0.184	0.003	0.772	0.774	0.311	0.366	0.364	0.035	0.745	0.501	0.170	0.057	0.805	0.380	0.01	0.02

OUTLINE		REFERENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	1330E BATE
PKG-B4					03/12/2013

Document Number: ITEV01600B4 Product Datasheet V1.0

Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2023/2/28	Rev 1.0	Preliminary Datasheet

Application data based on HL-23-05

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